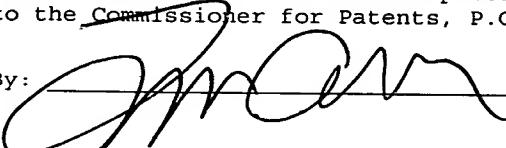




2826

GR 97 P 1903

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By: Date: September 26, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No. : 09/483,737 Confirmation No. 8769  
Applicant : Hansjörg Reichert et al.  
Filed : January 14, 2000  
TC/A.U. : 2826  
Examiner : Ahmed N Sefer  
Title: Method and Apparatus for Producing a Chip-Substrate Connection  
  
Docket No. : GR 97 P 1903  
Customer No. : 24131

Hon. Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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**AMENDMENT**

Sir :

In response to the Office action dated June 27, 2003, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.